

Product Change Notice: SEMC Series (eMMC) SD Cards Packaging Change

PCN.PG40.08.01.2018A

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About This Notice:	eMMC packing specification will be changed as attached. 1. Desiccant 2. Bubble wrap will be used as a spacer instead of empty trays
Effective Date:	November 2018 (exact date is TBD)
Change Details:	1.Desiccant Current: New: Image: Contract of the second
Affected Parts:	RP-SEMC08DA1, RP-SEMC16DA1, RP-SEMC32DA1
Datasheet(s):	As attached.
Notes:	*This change will not affect the performance of the product.

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